Electrical-, protocoland application layer validation of MIPI D-PHY and M-PHY designs

Roland Scherzinger

MIPI Application Expert Digital Test Division Agilent Technologies

## **Agenda**

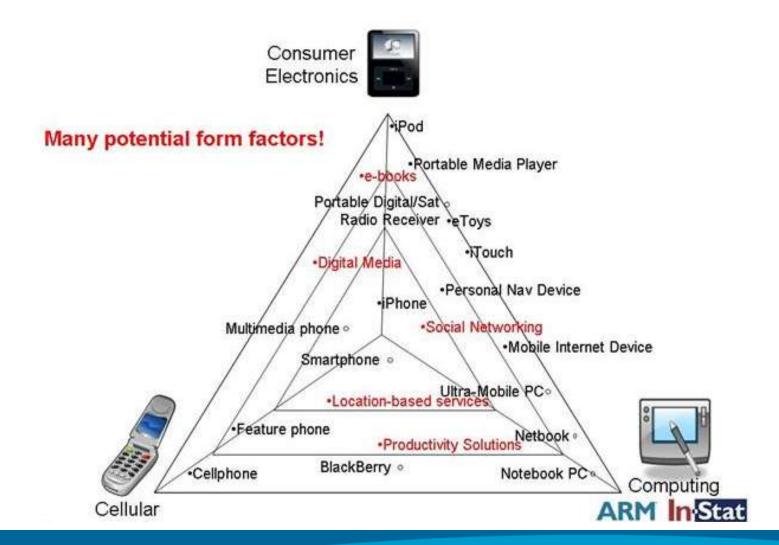
Introduction, Smart Device Overview

MIPI Interfaces in Smart Devices

Validating MIPI Interfaces

Outlook

#### **Smart Devices Overview**



### **Features of Smart Devices**

#### Internet, eMail, Organizer, Phone

- Wireless (WLAN, UMTS, LTE, ...)
   Imaging, Photo, Video, Movies
- High resolution Camera and Display Audio, Music
- MP3, WMA, AAC, ...

#### Maps

GPS, aGPS

**Book Reading** 

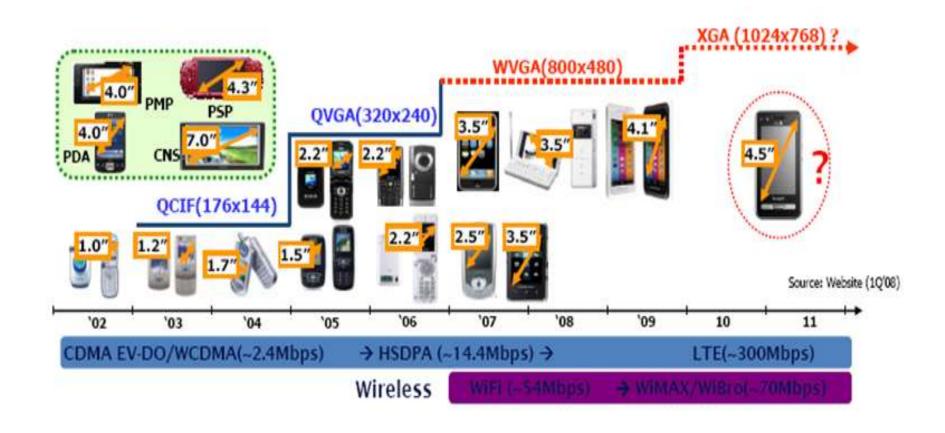
Gaming







## **Mobile (Smart) Device Evolution**



## **Agenda**

Introduction, Smart Device Overview

MIPI Interfaces in Smart Devices

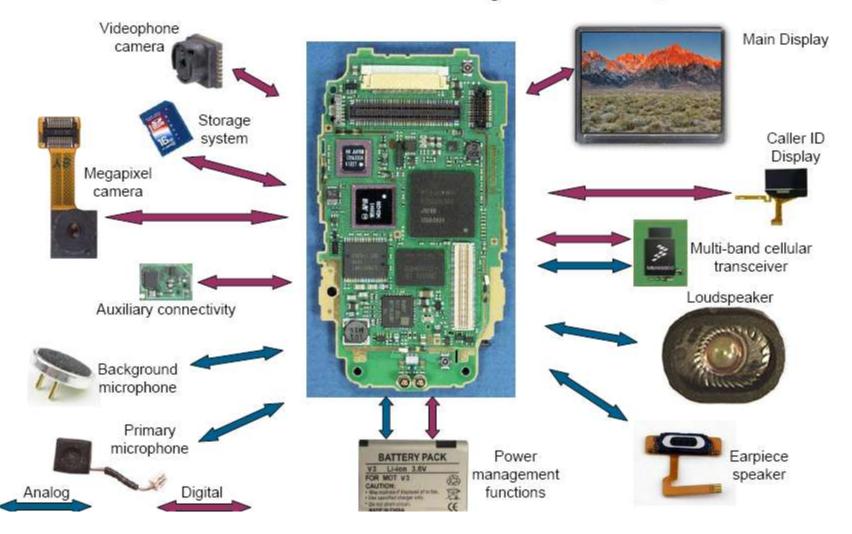
- MIPI Overview
- D-PHY Overview
- M-PHY Overview

Validating MIPI Interfaces

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## **Technology Challenges in Mobile Computing**

### Too Many Interfaces, All Different



#### **MIPI Interfaces in a Mobile Platform**

This picture is only an illustrative example for several ways of integration with the purpose of demonstrating MIPI diversity on interfaces

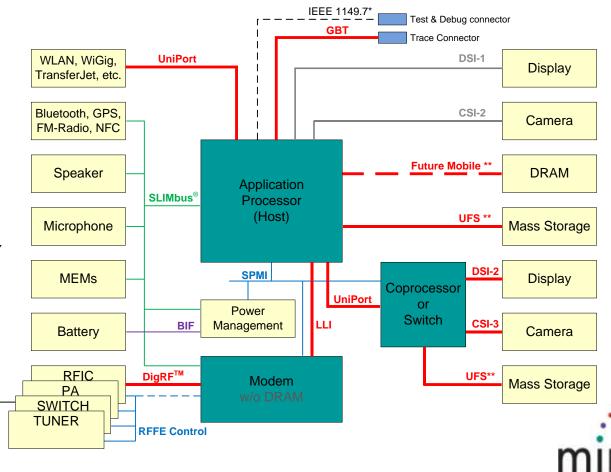
D-PHY basedM-PHY based

SLIMbusSPMI/RFFE

UniPort : UniPro™ + D-PHY or M-PHY

UniPro based IF technology are: UFS, CSI-3, DSI-2, GBT, UniPort

(\*) Transferred to IEEE (\*\*) Liaison with JEDEC

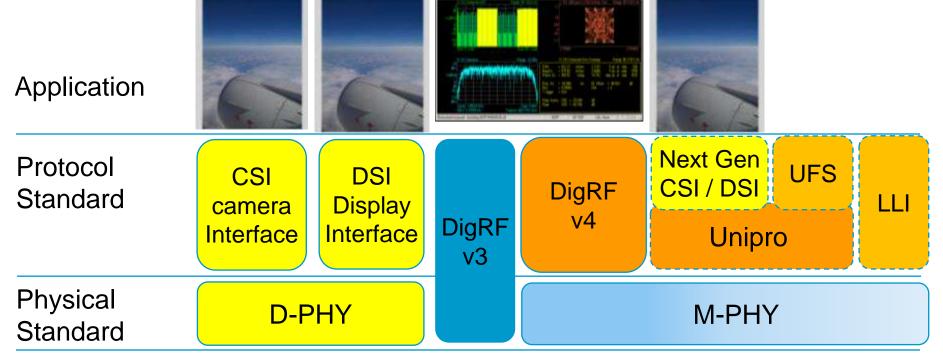


processor interface

## **Physical / Protocol / Application Support**



MIPI
Mobile industry
processor Interface



## **Agenda**

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## What is MIPI D-PHY?

MIPI D-PHY is a Serial Bus

Mobile Display

Mobile Camera

Mobile Controller

#### Why use MIPI D-PHY?



**Standard Bus:** Facilitates Integration and Interoperability

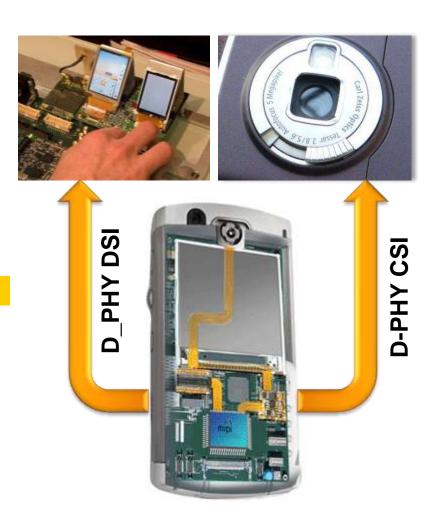


Performance: up to 4Gbs for high resolution camera and displays



Low power and high Scalability:

Multilane architecture



#### **MIPI D-PHY Characteristics**

#### **Data Lanes**

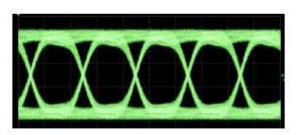
- High Speed Mode 80Mbps -1Gbps
- May go up to 1.5 Gbps in the future
- Low Power Mode < 10Mbps</li>
- Bidirectional

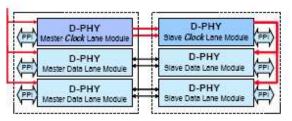
## Lane Scalability

Up to 4 Lanes + 1 clock lane

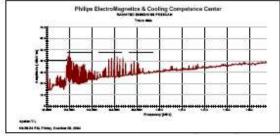
#### Power

- Low Operational power
- Very Low Standby power

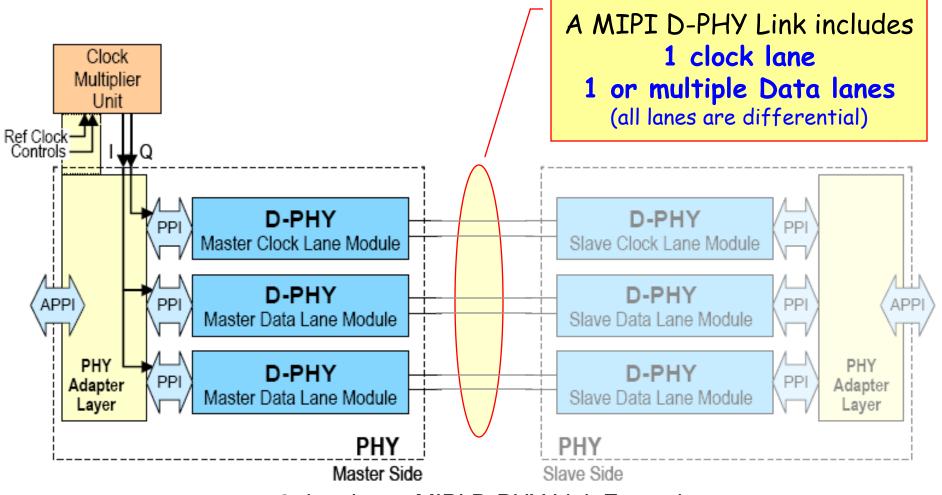








## **Anatomy of a MIPI D-PHY link**

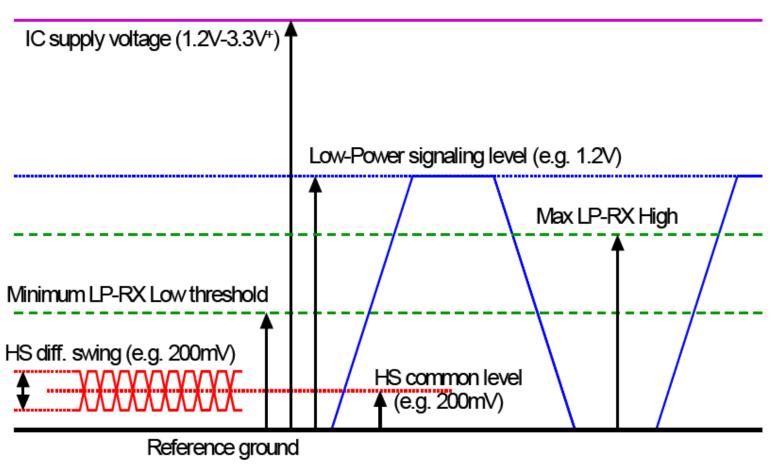


2 data lanes MIPI D-PHY Link Example

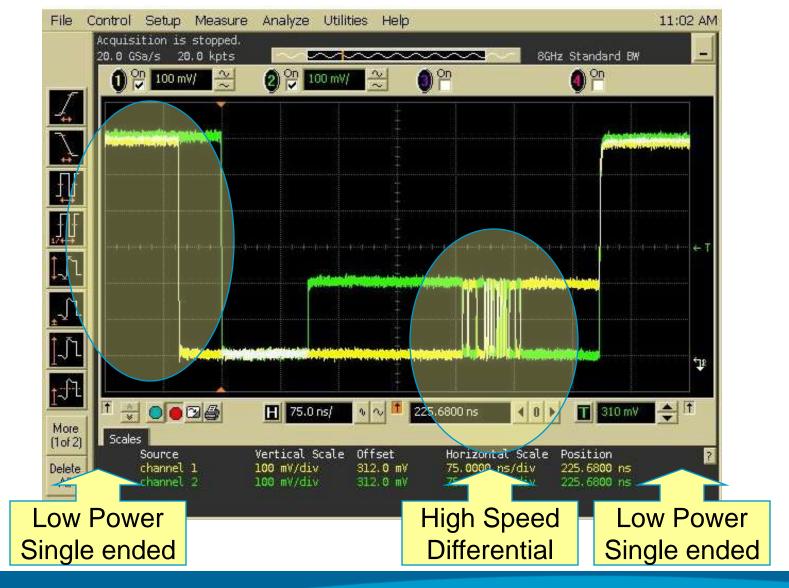
Master drives the clock

## MIPI D-PHY at the Physical Layer

Dual Signaling for high speed and low power transmission Dynamic termination



## **MIPI D-PHY Signals**



## MIPI DPhy DSI/CSI-2 Short Packet Structure

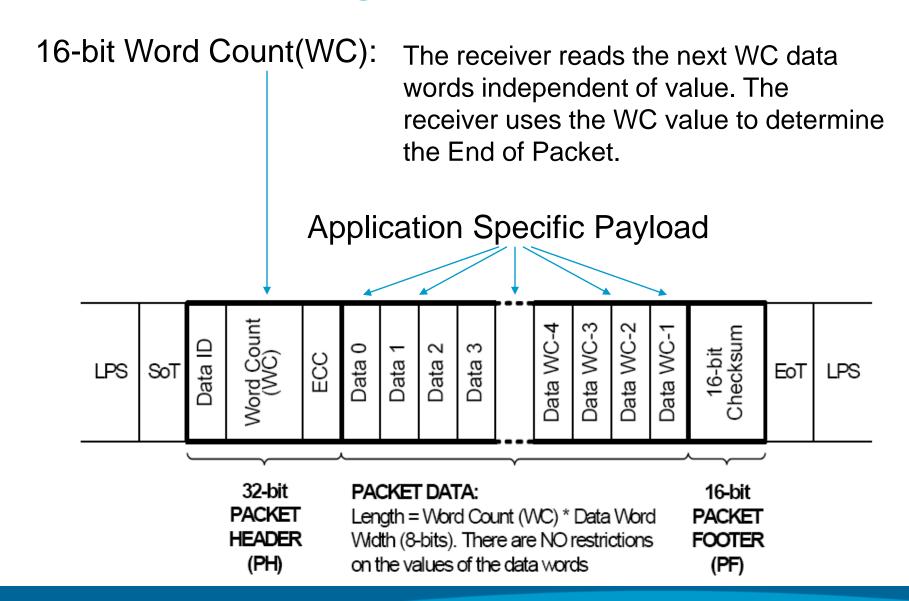
Note: The packet structure is identical for DSI and CSI-2. The difference is the interpretation of the Data ID field.

Data Identifier: Contains the Data Type Information (Short vs. Long) denotes the format/content of the Payload Data.

8-bit Correction Code: 8-bit ECC code for the Packet Header. Allows 1-bit error correction and 2-bit error detection.

32-bit SHORT PACKET (SH)

## MIPI DSI/CSI-2 Long Packet Structure



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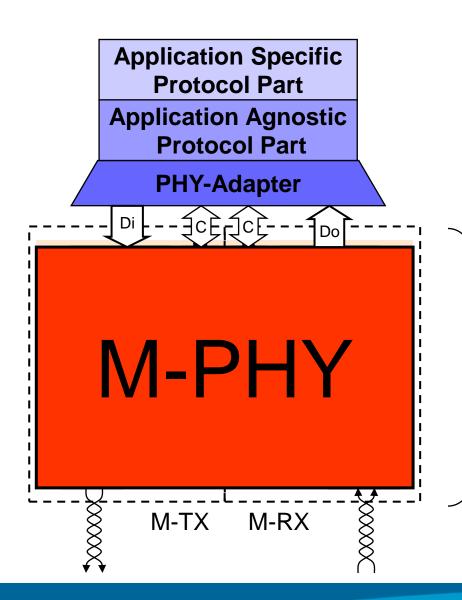
Validating MIPI Interfaces

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# **Main properties of M-PHY**

Main LANE characteristics		2 pins/wires, differential, unidirectional	
Minimum composition		Dual-simplex (4 wires)	
Media		0-30 cm PCB, micro coax <1.2 m cable optical waveguides	
Clocking method	HS	Embedded clock (8b10b) with or without shared RefClk	
	LS	PWM: Self-clocking SYS: Synchronous to RefClk	
Raw bitrates (8b10b coded)	HS	1¼ & 1½, 2½ & 3 , 5 & 6 Gb/s	
	LS	PWM: 10 kb/s-600 Mb/s SYS: RefClk rate	
RefClk frequencies		19.2 / 26 / 38.4 / 52 MHz	
Data BURST encoding		8b10b	
Power efficiency (overall)		<10pJ per payload-bit	
CDR at receive side		Yes for HS, No for LS(-only)	
TX pre-emphasis / RX equalization		No / Not specified	
Signal levels (supply independent!)		0 - 200mV <sub>RT</sub> - 400mV <sub>NT</sub> (large drive) 0 - 100mV <sub>RT</sub> - 200mV <sub>NT</sub> (small drive)	
Configuration	<u> </u>	Using protocol & PHY mechanisms	

## **Layered Interface Standards**



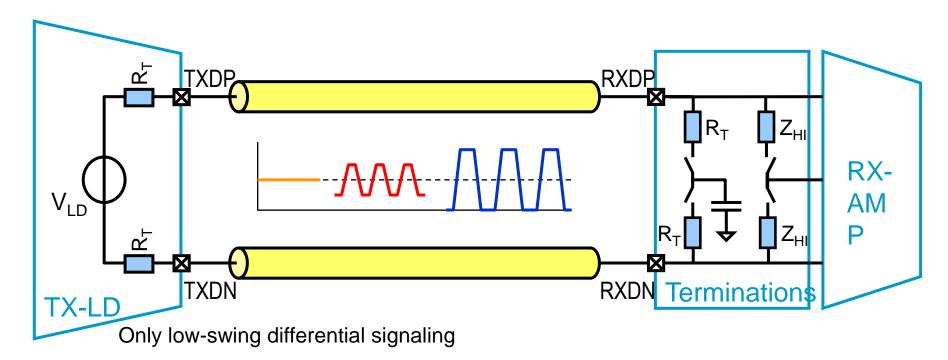
#### Applications:

- DigRF v4
- UniPRO
  - CSI / DSI / UFS / GBT
- LLI

M-PHY Scope



## **Electrical signal characteristics**



TX always provides LINE termination

Switchable RX line termination: operation with or without termination

RX can hold undriven LINE at 'differential-zero' with  $Z_{HI}$  impedances

Two different TX drive strengths: Large & Small (=Large/2)

Optional Slew-Rate Control for EMI reduction





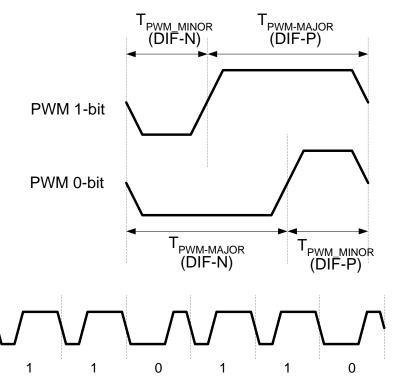
## Bit signaling schemes

#### NRZ

Non-Return-to-Zero (Trivial)

#### **PWM**

- Pulse-Width-Modulation
- Self-Clocking





# Comparison of D-PHY with M-PHY

Min. number of pins per direction	4	2
Minimum configuration	4 only unidir or half-duplex	4 dual-simplex=full-duplex
Minimal UniPRO configuration	8	4
Medium	<30 cm PCB, flex, micro coax	< 30 cm PCB, flex, micro coax, <1.2 m cable, optical
Data rate per lane HS	>80 Mb/s (Practical limit <1Gb/s) < 10 Mb/s	~ 1¼ , 2½ , 5 Gb/s ~ 1½ , 3 , 6 Gb/s 10k-600Mb/s
Electrical signaling HS	SLVS-200 LVCMOS1.2V	SLVS-200 SLVS-200 w/o RX-R <sub>T</sub>
HS Clocking method	DDR Source-Sync Clk	Embedded Clk
HS Line coding	None or 8b9b	8b10b
Power – Energy/bit	Low	Lower
Receiver CDR required	No	Yes
Suited for optical transmission	No	Yes
LP only PHY's	Disallowed	Allowed





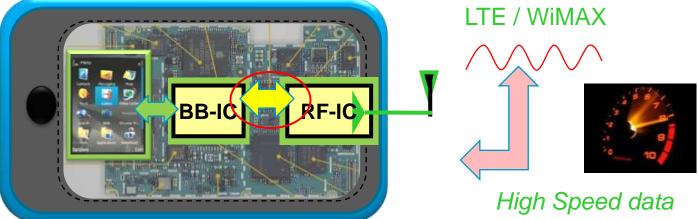
## **DigRF V4 Overview**

DigRF v4 is the next generation link between the BB-IC and RF-IC in a mobile device, enabling LTE and WiMAX data rates

Bus between BB-IC and RF-IC must support high traffic flows

4G standards (LTE, WiMAX) enable downlink speed of over 300

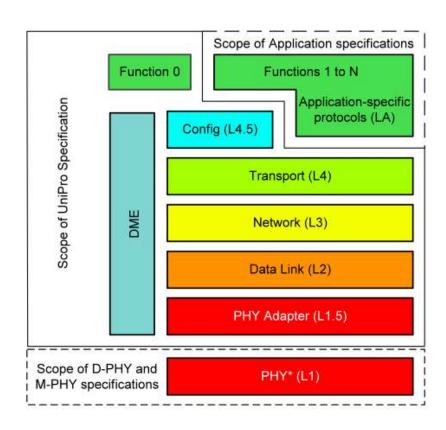
MBit/s



DigRF V4 is an enabling technology for LTE and WiMAX Applications

#### **UniPro Overview**

- D-PHY and M-PHY
- High Scalable Bandwidth with low pincount
- Low power consumption
- Reliable packet based, latency-aware Traffic Classes
- Network architecture
- Connection management
- Device discovery
- Remote configuration
- Security



Layered Model of UniPro v1.5

\*MIPI D-PHY or MIPI M-PHY

## Low Latency Interface (LLI) Overview

The LLI interface allows sharing a DRAM memory between 2 chips for data and program. The main motivation for LLI is cost reduction.

The LLI specification defines several logical layers to help to make the specification more understandable:

- Transaction layer: exchanges memory mapped read/write transactions and signals between 2 chips.
- Data link layer: provides several independent virtual channels between the 2 chips.
- PHY adapter layer: provides an interface to the physical media. Focus first on serial MIPI M-PHY. Ensure reliability as necessary.
- Power management. Interface control for optimal power consumption; definition of the power states.
- Boot and reset
- Test

## **Agenda**

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Validating MIPI Interfaces

- Testing Overview
- D-PHY Testing
- M-Phy Testing

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## **Test Applications**

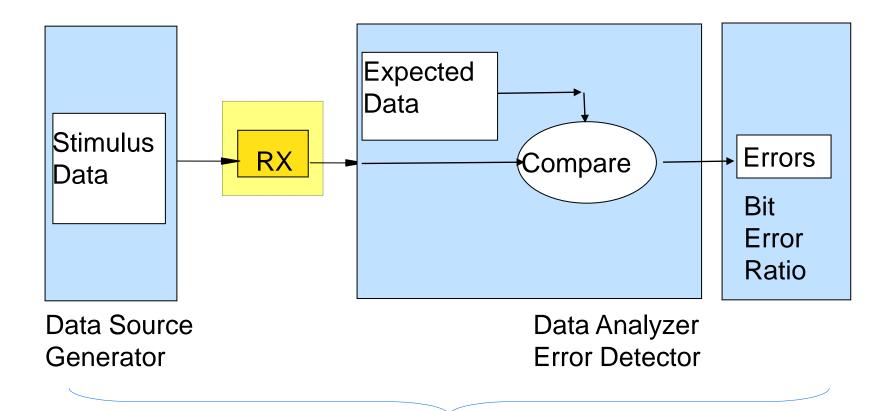
### **Electrical Layer**

- TX & RX Compliance (Scope & Generator (BERT))
- BringUp & Debug (Scope)

#### **Protocol & Application Layer**

- Protocol Compliance (Protocol Exerciser / Analyzer)
- BringUp & Debug (Protocol analyzer or Scope)
- Device Emulation (Protocol Exerciser)
- Performance Validation (Protocol Exerciser)
- Application testing (Software Add-ons for Protocol exerciser)

# How to electrically test an RX Bit Error Ratio Test Principle



Bit Error Ratio Tester (BERT)

## **Agenda**

Introduction, Smart Device Overview

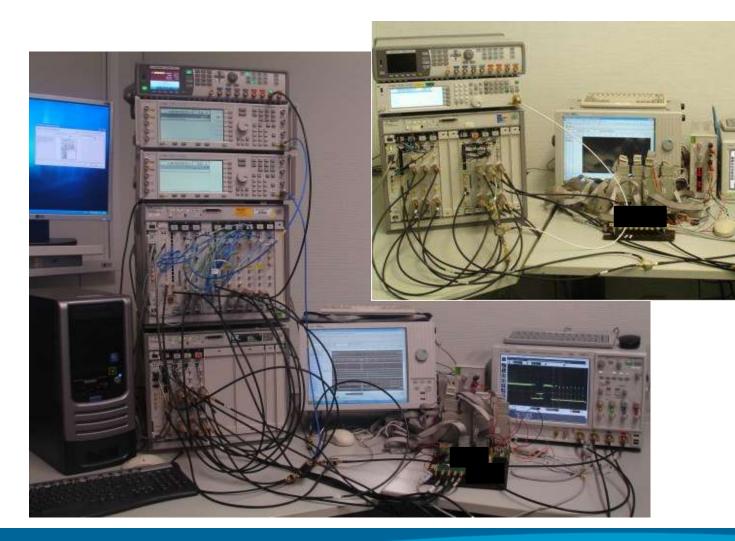
MIPI Interfaces in Smart Devices

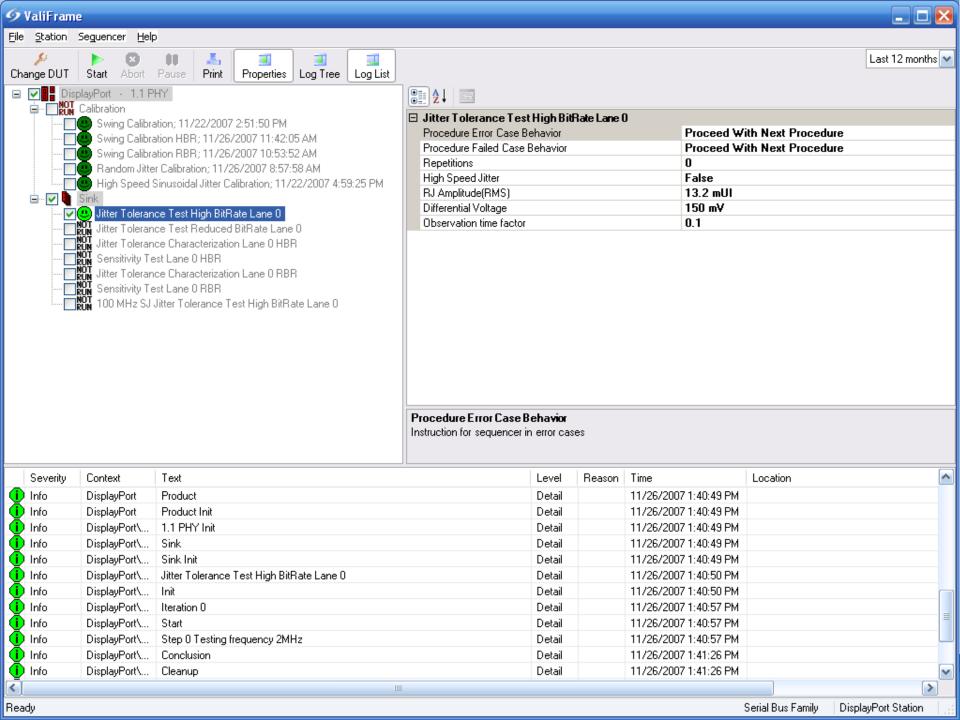
Validating MIPI Interfaces

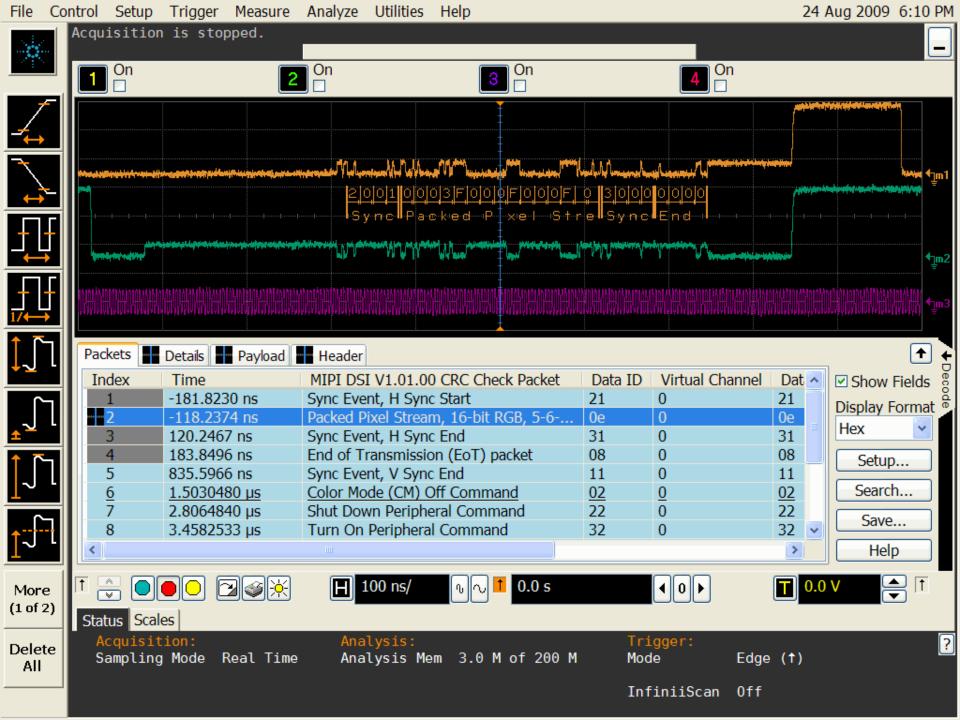
- Testing Overview
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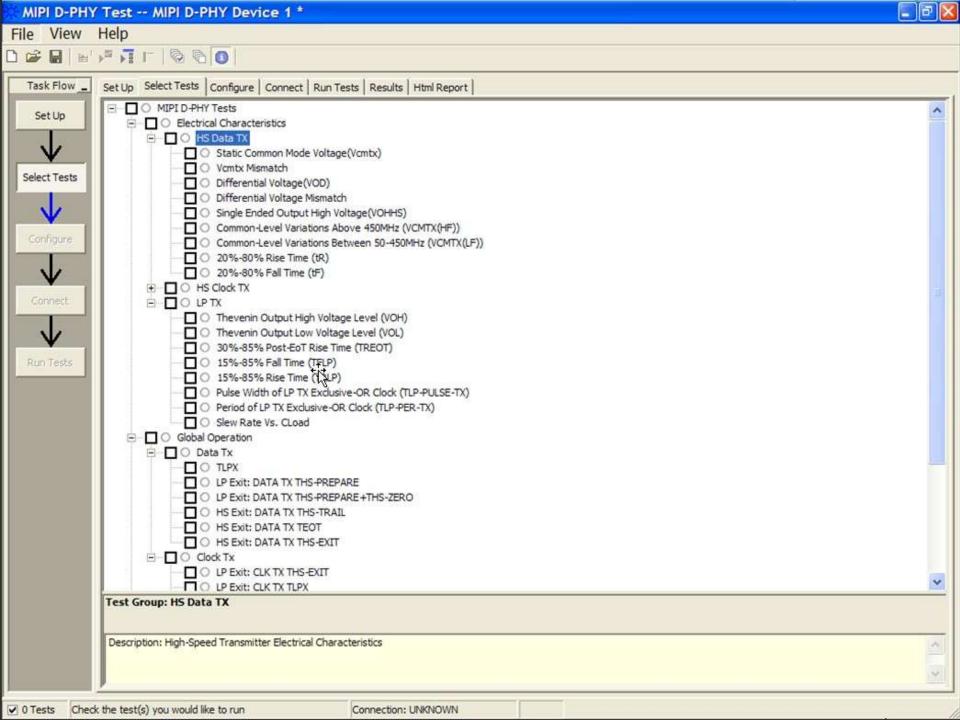
Outlook

# **Agilent D-PHY Physical Layer Test Solution Integrated Rx and Tx Test Setups**



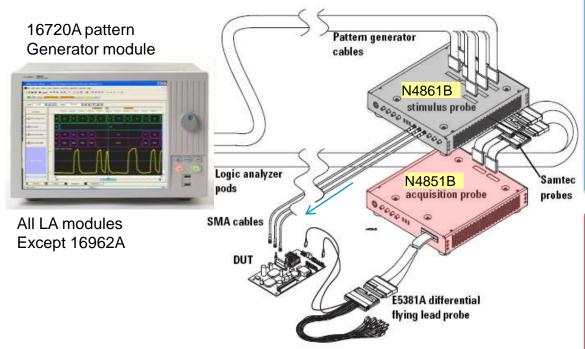






## MIPI D-PHY Protocol Test System configuration

**Protocol Stimulus and Analysis** 



#### Notes:

- Loopback board orderable N4850-66402 for around \$750.
- Dynamic termination board available from UNH-IOL.

#### N4861B Stimulus Probe

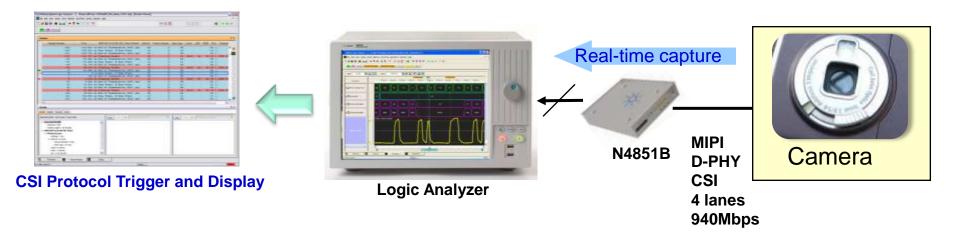
- Speed: 1Gbps per lane
- 3 lanes support
- CSI & DSI stimulus generation
- Error injection
- Voltage control
- Timing control
- High Speed and Low power mode

#### N4851B Analysis Probe

- Speed: up to 1Gbps per lane
- 4 lanes support
- Flying leads or soft touch
- Full Protocol Triggering
- Real time error detection
- CSI & DSI packet viewer
- High Speed and Low power mode

### **Test Model #1: Camera Sensor Test**

#### Functional Analysis



**Capture Traffic in real-time** 

**Protocol Level Trigger and Display** 

**Real time Errors detection** 

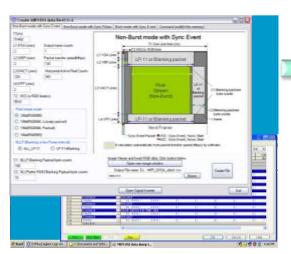
**Compliance test** 

#### Notes:

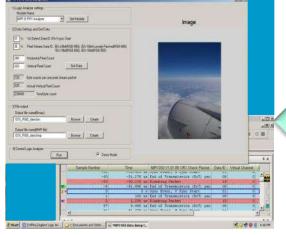
- Analyzer operates in high impedance mode
- Dynamic Termination required on target System
- Camera= bus Master



Test Model #2 : Display Module Evaluation Functional Stimulus and Analysis



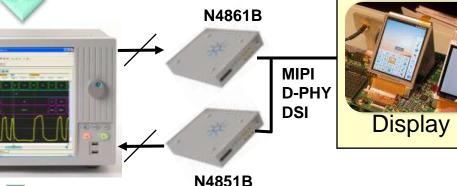
**DSI Packet & Image Generation** 



**DSI Packet & Image View** 

Initialization Commands
Data File

Send Stimulus to Display Device



Logic Analyzer Real-time capture of Bus activity

#### Notes:

 Dynamic Impedance required on target system if bus-turn around

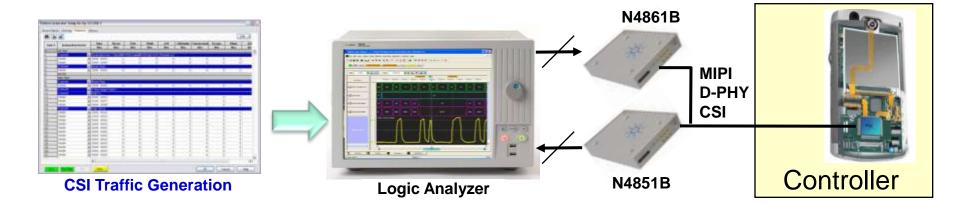




#### **Test model #3: Camera Emulation**

#### Functional Analysis

#### Send Stimulus to Controller Device



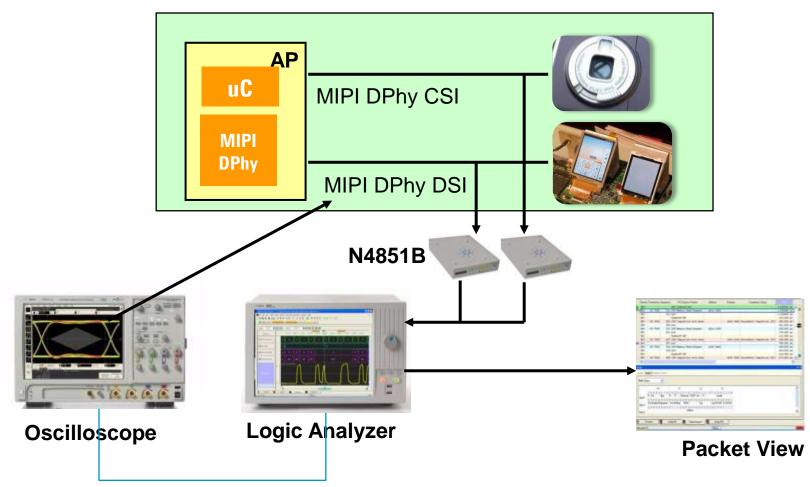
**Challenge: simulating various CSI devices** 

**Generate Real-time CSI traffic** 

1Gbps on 3 lanes

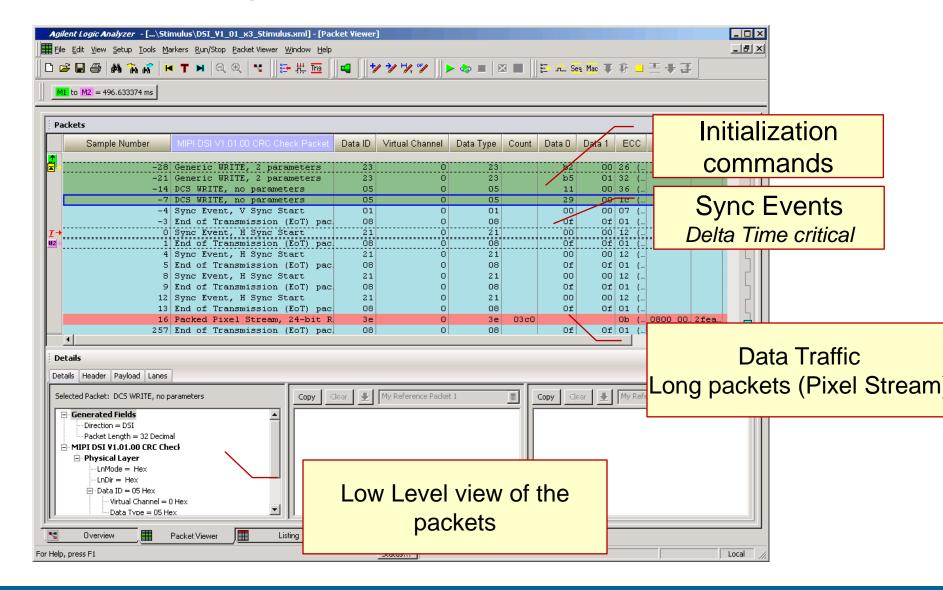
**Capture and replay** 

# Test model #4 : Controller, Display & Camera Integration



ViewScope for cross triggering and time correlated measurement

### **Protocol Analysis**



#### **Agenda**

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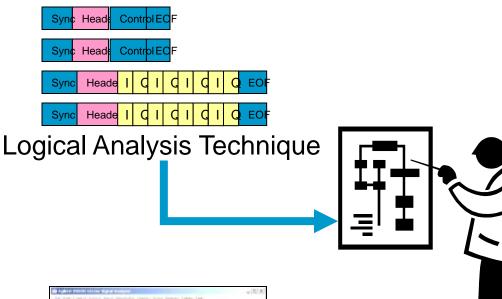
Validating MIPI Interfaces

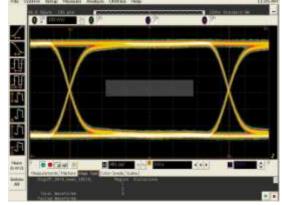
- Testing Overview
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**Knowledge/Techniques Required for DigRF** 

**Analysis** 





Signal Integrity Knowledge

The property of the property o

Digital I/Q Analysis Technique

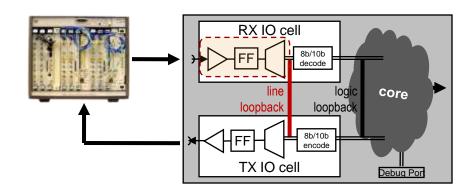
Various knowledge/techniques are required for DigRF analysis. In particular there are new *high* speed digital physical layer and protocol level testing and validation required.

# Receiver Test With BERT Generator and BERT Error Detector

Focus on receiver characterization and R&D level debugging

Utilizes the line loopback mode

Test pattern: all kinds of test pattern supported



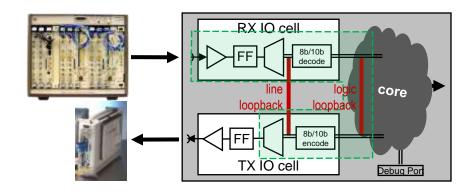
## Receiver Test With BERT Generator and DigRFv4 Exerciser

Receiver characterization and system timing stress test

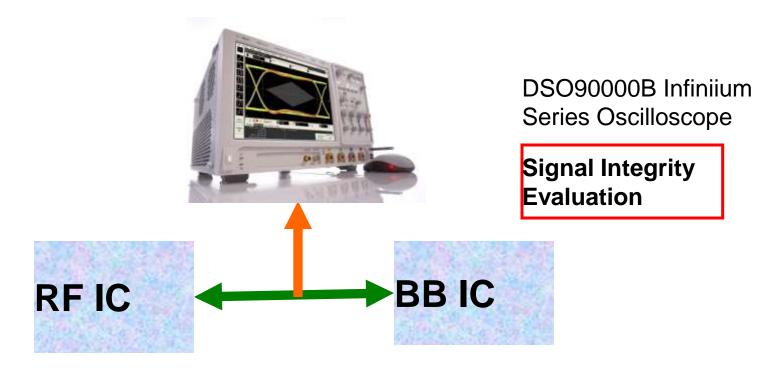
Utilizes the logic loopback mode with additional limited support for line loopback

#### Test pattern:

DigRF4 commands with payload and checksum in logic loopback mode, and PRBS 7 and PRBS 15 in line loopback mode



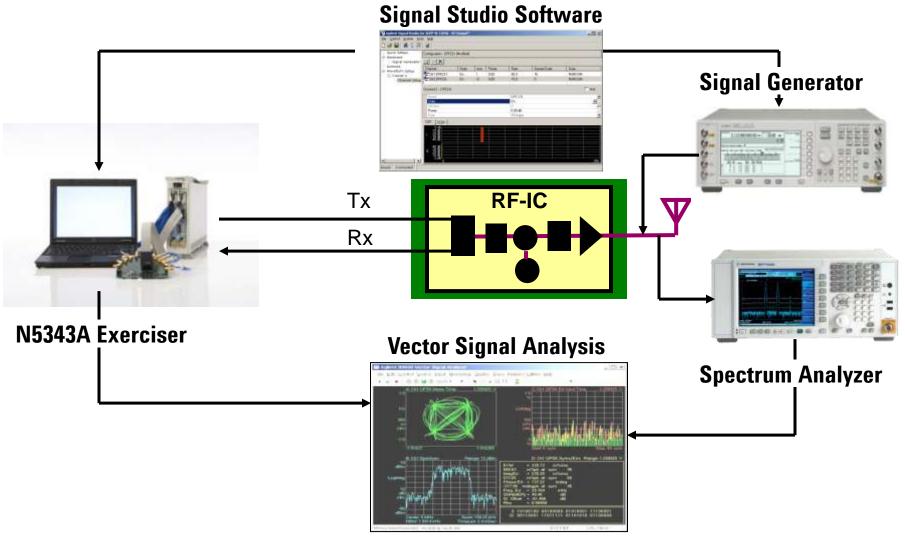
#### **Digital Signal Integrity Evaluation**



DigRF evaluation begins with the digital physical layer evaluation. Digital quality is tied directly to the final RF quality

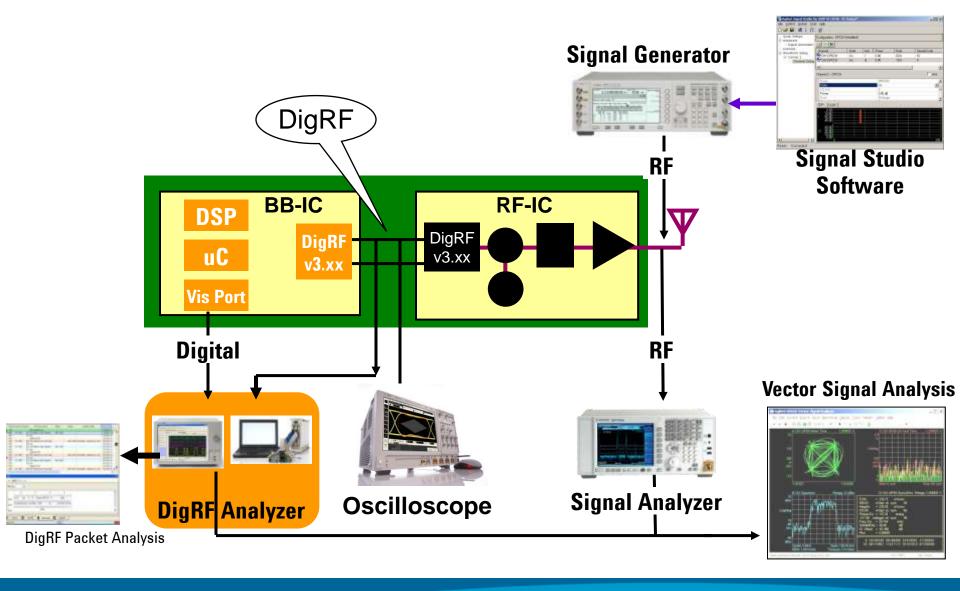
Preliminary Compliance test with UDA

## DigRF v3/v4 RF-IC Unit Testing Environment



Modulation Analysis and C/N Measurement

## RF-IC, BB-IC, Integration Testing Environment



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#### What will happen in 2011 / 2012?

D-PHY evolving towards 1.3 .. 1.5 Gbit/s bandwidth

M-PHY Gear 2 followed by Gear 3

3D support for Display and Camera

CSI-3, DSI-2 and UFS on UniPro 1.4 / M-PHY Gear 2

Low Latency Interface 1.0

- UniPro based applications and LLI will require protocol aware stimulus as both protocols are implementing real-time handshaking.
- Agilent will ensure appropriate test equipment availability at the right time.

## Do you have any questions?